

# TPC Parameters for ILD Integration and the DBD Status 6 May 2010

Rocky mountains symbolizing "we've got a rocky road ahead before we get to the linear collider"...

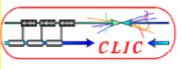












## Integration: hardware model iteration # 2

- --Iteration # 1 at wpmtg103 on 20100422 was only looking at the effect of the electronics (cables and pipes), using Antoine's ROB as a basis (263mm  $\times$  282mm containing 16  $\times$  16 S-Altros). There are two ways to improve, ergo this new iteration:
- --a) The 'TPC envelope' required by the MDI group must be included in the thinking.
- --b) Email exchange with Dan; we concluded that it is better if the basic unit is smaller in size and number of channels: a proposal follows.

## « MDI parameters» Starting with point a),

here is the 'TPC envelope' as set up by the MDI-integration group for the LOI

TPC envelope

 $R_o = 1808 \text{ mm}$ 

 $R_i = 330 \, \text{mm}$ 

L/2 = 2350 mm

TPC sensitive volume/area

 $R_{o} = 1743 \text{ mm}$ 

 $R_i = 395 \, mm$ 

L/2 = 2250 mm

Volume = 40.7 cubic meters

Area/endcap= 9054145mm^2

Space for the inner FC = 65mm

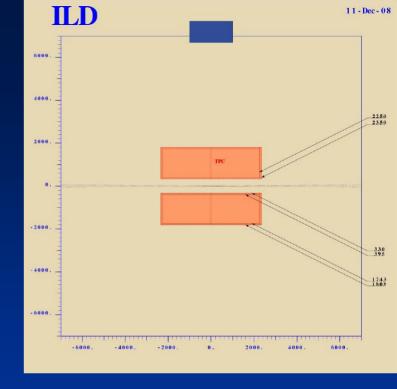
Space for the outer FC = 65mm

Space for the endcap = 100mm

('Space' is provisional and to be filled by

us, of course)

Ron Settles MPI-Munich LCTPC integration model



#### DETECTOR OPTIMISATION

Model N		GLD	$\operatorname{GLD}'$	GLD4LDC	LDC4GLD	LDC	LDC	ILD
Sin. Na	ight	-11/	Va	rvin	a ve	SAME.	ior	okka
B field (T)		2.0	3.5	4.0	3.0	3.5	<del>IQ</del> r	3.5
Be impine for v		15.0	14.0	1/0	15.5	14.0	13.0	14.5
Ve Ux Cecuetry		<del>e tne LOI</del>			ladders			ladders
D	1	0				0.111.		
	$R_{min}$	17.5	16.0	15.0	16.5	15.0	14.0	16.0
Barrel	Lavere		4 cylinders 2 cynnel			2 cylinder		
Share	Radii	90, 160, 230, 300		161.4, 270.1			100, 200	
TPC	$R_{min}$	437	435	371	371		395	
drift	$R_{max}$	1978	1740	1520	1931	1733	1511	1739
region	$z_{max}$	2600	2350	2160	2498	2248	2186	2247.5
TPC pa		256	217	196	260	227	190	224
CAL	$R_{min}$	2100	1850	1600	2020	1825	1610	1845
barrel	Layers	33 28.4		20(thin) + 0(+1k)			20+9	
	Total $X_0$				23.6			
ECAL e	endeap $z_{min}$	2800	2250	2100	2700	2300	2550	2450
HCAL	Layers	46	42	37		48		48
barrel	$R_{max}$	3617	3260	2857	3554	3359	3144	3330
$\lambda_I$ (ECA	AL+HCAL)	6.79	6.29	5.67		6.86		6.86

TABLE 2.1-

Geometrical parameters of the baseline detector models used for the optimisation studies (GLD, GLDPrime, GLD4LDC, LDC4GLD, LDCPrime and LDC). Also shown are the corresponding parameters for the ILD baseline detector. Unless otherwise specified, values are shown in units of mm.

## « MDI parameters»

## Conclusion point a):

TPC sensitive area

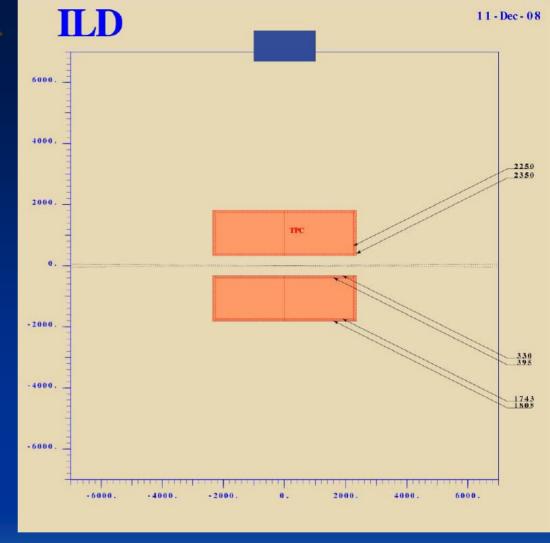
 $R_o = 1743 \text{ mm}$ 

 $R_i = 395 \, \text{mm}$ 

Area/endcap to be instrumented with MPGDs = 9054145mm^2

= 1998848

4mmx1mmpads/endcap



« MDI parameters»

Point b):

Readjust the sizes from interation #1 based on the TPC envelope for Catherine Clerc.
Reminder: we propose to define one "generic" TPC (not two) for MPGD (i.e., neither µgas- nor gemspecific).



## <sub>[трс</sub> interface parameters]

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Issue	
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#### 1. Technological description

Each endplate ≈ 10 m<sup>2</sup>

- ✓ µmégas 7\*3mm² i.e. 0.55Mch/endplate
- ✓ Gems: 1\*5mm² i.e. 2.3 Mch/endplate

#### 2. Overall dimensions

400 KG/endplate, ≈ 2t full TPC

3. Support

3 tie rods from each endplate face to HCal barrel

#### 4. Services

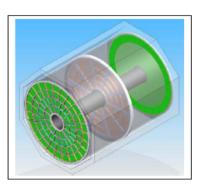
#### Cabling (µmégas)

- 80 modules each side.
- For each module (6800 channels):
- 1 HV cable
- 1 double optical fibre
- 1 low-voltage 32A cable

Each side: 80 HV+80 Double Fibres+80 LV(32A) = 240 cables

#### Cooling:

160 W to remove (becomes negligeable is power pulsing can be fully implemented.) But to be checked With power pulsing 0.5mW per channel



### Adrian's simulation: bottom line $\Rightarrow$ want small pads

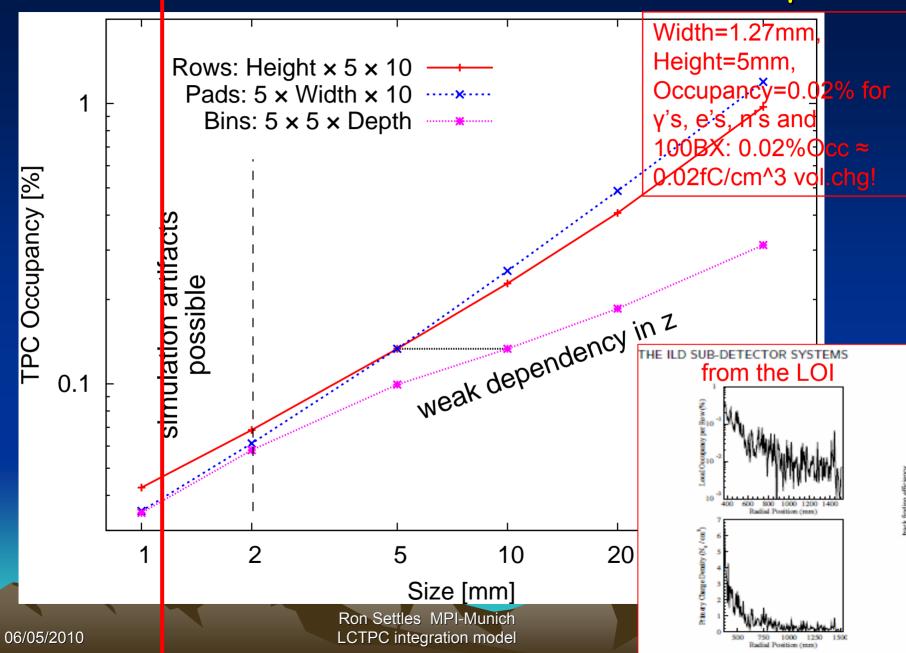


FIGURE 4.3-4. Occupancy for  $xyz = 1 \times 5 \times$ 

"Generic" again means don't worry about sector/module shapes here. Suggestions will be made as to subdivide our readout units so that whatever shapes we decide on might be accommodated.



Also the shapes we decide on will depend on the

outcome of Dan's studies

	mass kg	material %X <sub>0</sub>	microns	stress Mpa ield:		A	
241)			()				
LP1	18.87	16.9	33	1.5			
Lightened (all aluminum)	8.93	8.0	68	3.2	H	1	
	Al 7.35 C 1.29		< 168* alues for the alum	< 4.8° ninum only)	A	5	
Space-Frame	8.38	7.5	23	4.2			
						6	
Material: space	-frame	has slightly	more mater	ial than the	e Al-C hybri	d.	

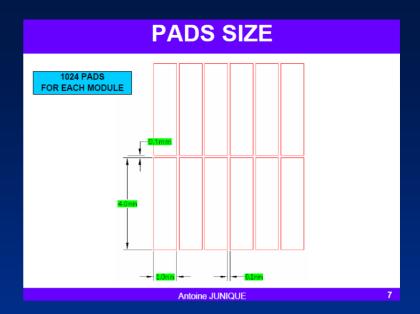
## Electronics: both micromegas and gem have agreed to use S-Altro

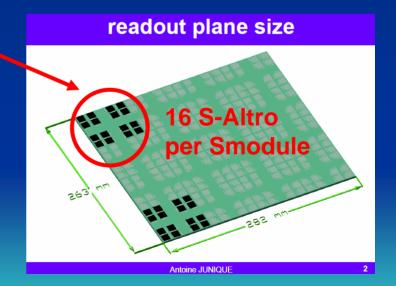
## Since the word 'module' has been used for different things, try new notation to reduce (or increase?) the confusion:

Smodule	16 S-Altro	1024 pads
ROB-n	2 <sup>n</sup> Smodule	2 <sup>n</sup> x 1024 pads
ROB-0	Smodule	
ROB-1	2 x Smodule	2048 pads
ROB-2	4 x Smodule	4096 pads
ROB-3	8 x Smodule	≈ LP 'module'
ROB-4	16 x Smodule	Antoine's ROB

#### Smodule - smallest unit

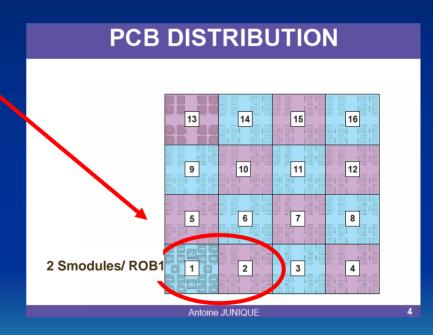
- --pad pitch: 4.1 x 1.1mm^2
- -- 16 S-Altro/Smodule
- --1024 pads/Smodule
- $\Rightarrow$  4635.4 mm<sup>2</sup>/Smodule





### Sizes

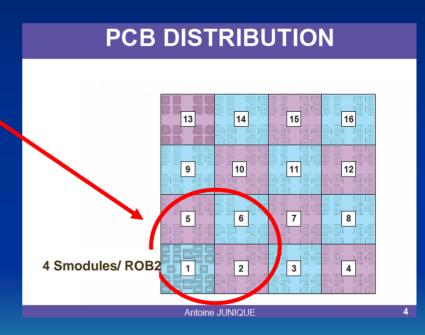
- --2 Smodule per ROB-1 = 2048 pads/ROB-1
- ⇒ 9270.8 mm<sup>2</sup>/ROB-1



2 Smodule per ROB-1

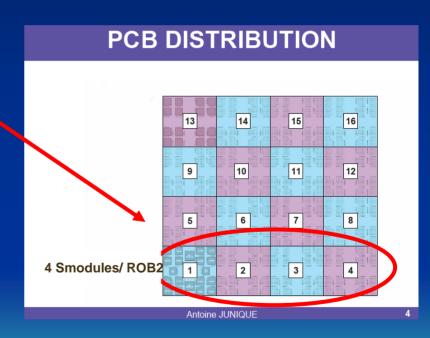
#### Sizes

- --4 Smodule per ROB-2 = 4096 pads/ROB-2
- $\Rightarrow$  18451.5 mm<sup>2</sup>/ROB-2



4 Smodule per ROB-2

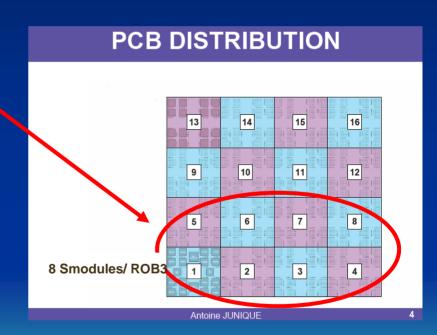
- --4 Smodule per ROB-2 = 4096 pads/ROB-2 ⇒ 18451.5 mm<sup>2</sup>/ROB-2



4 Smodule per ROB-2

#### Sizes

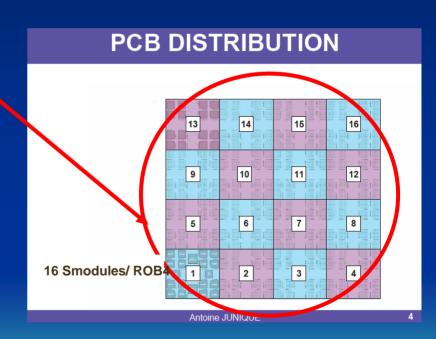
- --8 Smodule per ROB-3 = 8192 pads/ROB-3
- $\Rightarrow$  37083.0 mm<sup>2</sup>/ROB-3



8 Smodule per ROB-3

#### Sizes

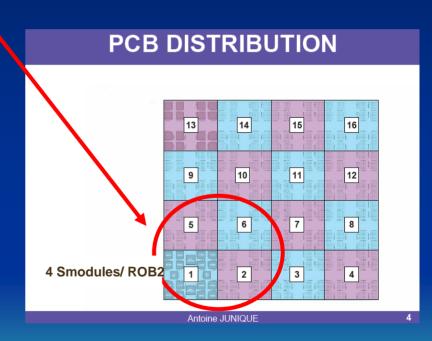
- --16 Smodule per ROB-4 = 16384 pads/ROB-4
- $\Rightarrow$  74166.0 mm<sup>2</sup>/ROB-4
  - = Antoine's 'ROB'



16 Smodule per ROB-4

## Example: subdivide the endcap using ROB-2...

- --2 Smodule per ROB-2 = 4096 pads/ROB-2
- ⇒ 18542 mm<sup>2</sup>/ROB-2
- --R\_endcap ~ 395mm to 17143mm
- $\Rightarrow$  9054145 mm<sup>2</sup>/endcap
- ⇒ 488 ROB-2/endcap

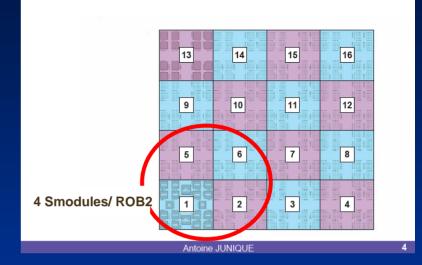


4 Smodule per ROB2

--ROB-2 size:  $\frac{1}{2}$  263 x  $\frac{1}{2}$  282mm<sup>2</sup>  $\approx$   $\frac{1}{2}$  x Dan's LP1 "ROB"

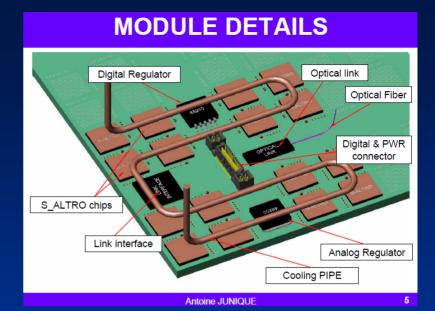


#### **PCB DISTRIBUTION**



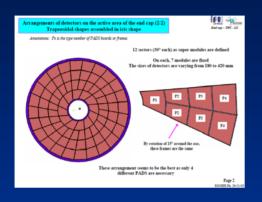
#### # Channels

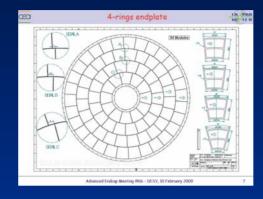
- --64 pads/S-Altro
- -- 16 S-Altro/Smodule
- -- 4 Smodules/ROB-2
- $\Rightarrow$
- --1024 pads/Smodule
- --4096 pads/ROB-2
- --488 ROB-2/endcap
- --1998848 pads/endcap

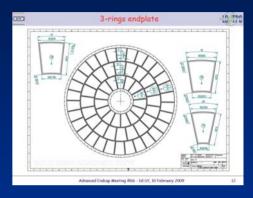


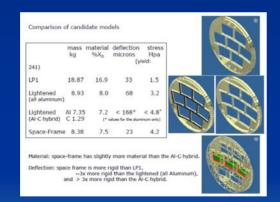
This is just an example. Different ROB-n can be used across the endcap, depending on the shapes of the different ROBs

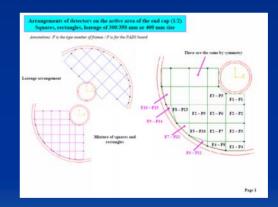
## This is a job for the experts...











### Cooling (slide from mtg103)

Also, these two strategies are different: Bart cools a timepix chip. This corresponds roughly to one ROB in a pad TPC (a "cooling unit") = 11 W at 40MSPS, where Antoine's "cooling unit" is one Sector = 0.050ME at AO MSPS.

Cooling tube routing

Lygor returning

Cooling tube routing

Lygor returning

Cooling tube

Cooling

Digital Regulator
Optical link
Optical Fiber
Digital & PWR
connector

S\_ALTRO chips
Link Interface
Analog Regulator
Cooling PIPE

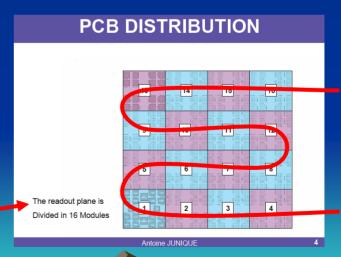
Antone JUNIQUE

At Aleph, our "cooling unit" was ~ 1 W, roughly equivalent for this lctpc case 1 Smodule = 16 S-Altros

= 0.7 W at 40 MSPS or

= 0.4 W at 10 MSPS. Should

Bart use this?



## Cables (slide from mgt103)

- -- Cable for fieldcage: one 70 kV cable,  $\phi \sim 15$  mm (Catherine's estimate is o.k.)
- -- Cables for MPGD, gating, clock, readout optical fibre, etc:  $\sim 10/ROB$  (depends on layout)  $\Rightarrow$  material small.
- -- Power cables  $\Rightarrow$  material large. This is important because the material is large and is very sensitive to the cable layout scheme, and we have not had enough time to work this out. We must try to do this within the next few weeks.

#### X 0 Thicknesses (slide from mtg103

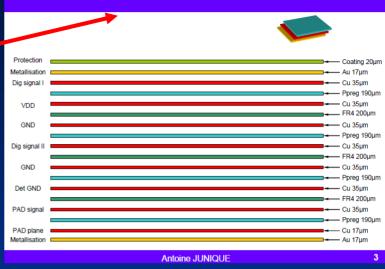
Sum of these plus S-Altros ~ 5 % X\_0

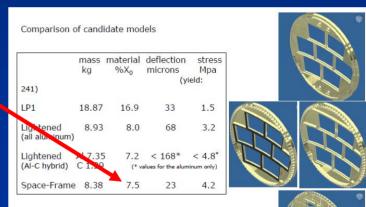
Dan estimated at last meeting the space-frame thickness ~ 8 % X\_0 for the LP size. We don't know yet how this translates to the LCTPC size.

Cooling (my guess, needs confirmation) ~ 2% X\_0

Cable layout --- work in progress --- but it looks like the above X 0 may be double on Settles MPI-Munich above X 100 may be double on Settles MPI-Munich integration model

#### LAYER STACKUP





Material: space-frame has slightly more material than the Al-C hybrid.

Deflection: space frame is more rigid than LP1, ~3x more rigid than the lightened (all Aluminum), and > 3x more rigid than the Al-C hybrid.

### LCTPC milestones

2006-2012 Continue LCTPC R&D via small-prototypes

and LP tests

2013 Decide on all parameters

Final design of the LCTPC

Four years construction

2019-20 Commission/Install TPC in the ILC Detector